f Fermilab

Fermi National Accelerator Laboratory
P.O. Box 500•Batavia,Illinois•60510-500
(630) 840 - 5042 jaws@fnal.gov

Particle Physics Division-CMS, MS 205
FAX # 630/840-2194

March 12, 2002

CCA Chip Packaging Instructions

There are 16 CCA bare die in the waffle pack (dice carrier).

The die are 24 mils (0.024 inch, 0.609mm) thick and should be packaged in a 2.7mm thick, 14mm x 20mm QFP package.

Package the parts in 128-pin QFP packages. See the attached wire bonding diagram. Use blind assembly to package all of the dice.

Label the parts as CMS CCA as shown on the attached diagram. Place the assembly or labeling date on the packages as shown on the attached diagram.

Reject instructions; scrap.

*** Please return the die carrier to Fermilab. ***

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Fermilab P. O. # 543377

Wafer Lot # T17Z (16 Die)

Turn Around Time: Standard

Fermilab Contact Person:

Julie Whitmore
(630) 840-5042

Bill To Address:

Fermilab
Accounts Payable
P.O. Box 500
Batavia, IL 60510
USA

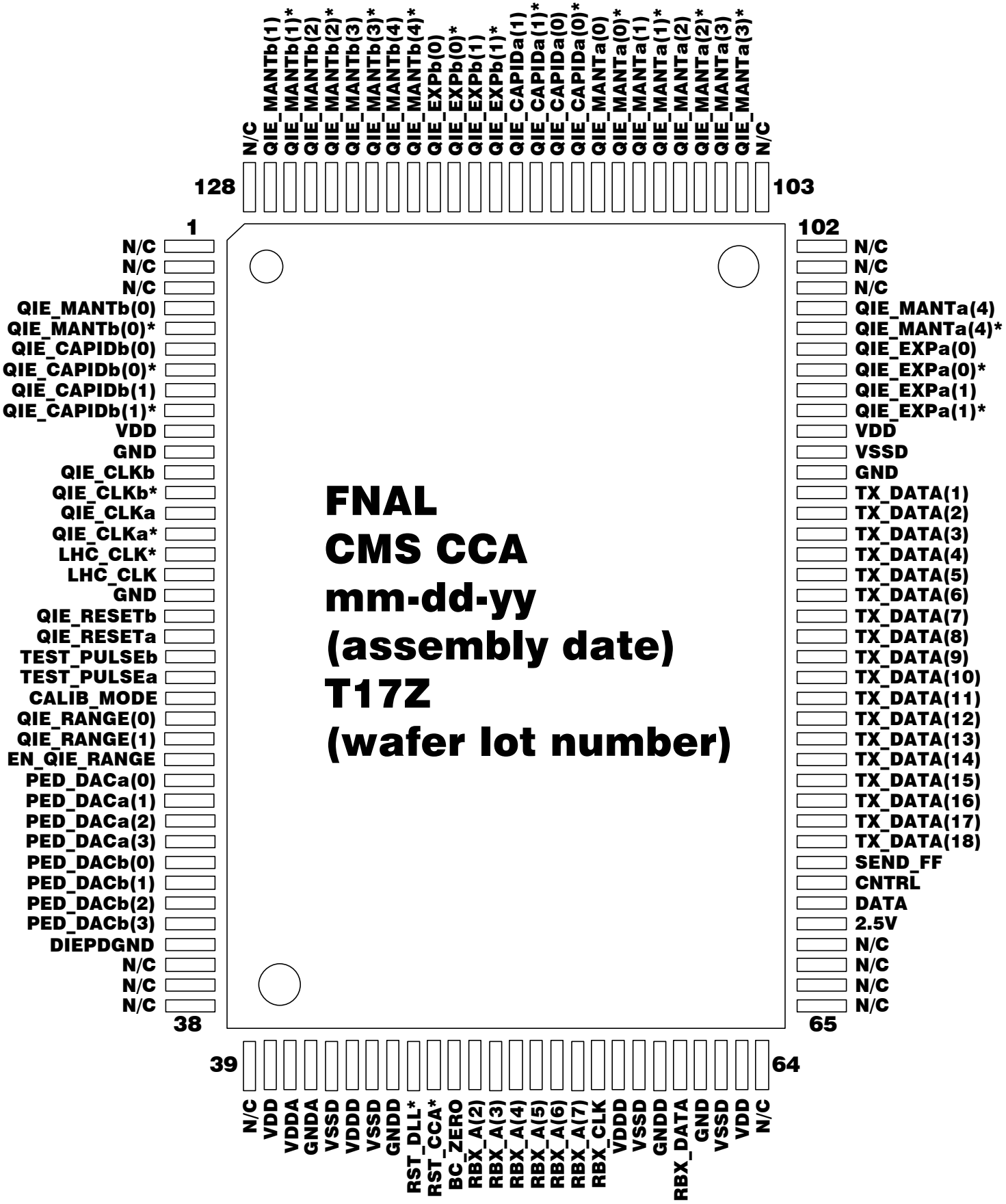
Ship To Address:

Fermilab
Receiving/Warehouse 2
Kirk Rd. & Wilson St.
c/o Julie Whitmore
Batavia, IL 60510
USA

03/07/02

CMS CCA

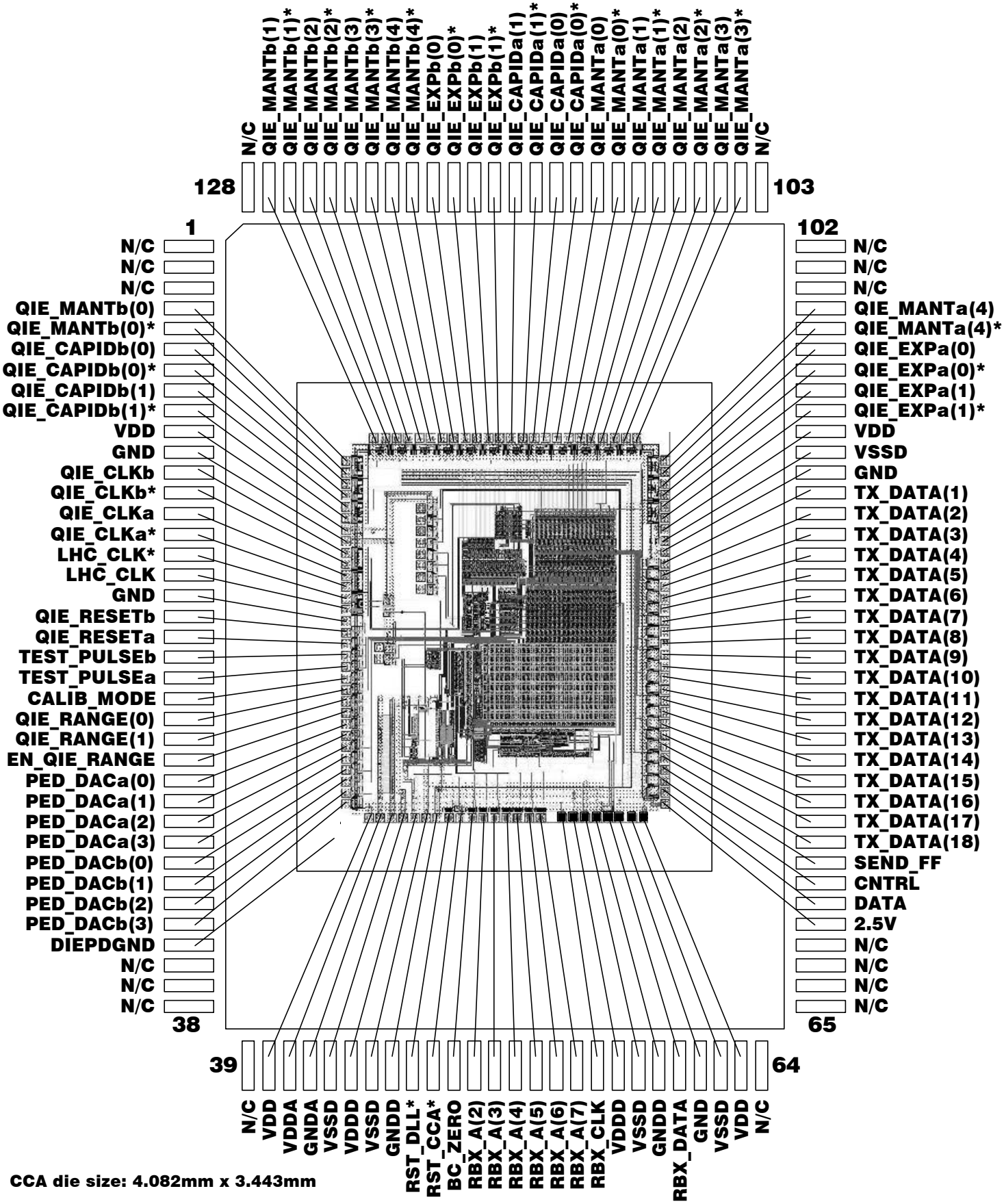
128-Lead QFP Package Pin Assignments



03/07/02

CMS CCA

128-Lead QFP Package Bonding Diagram



CCA die size: 4.082mm x 3.443mm